

FDMA2002NZ

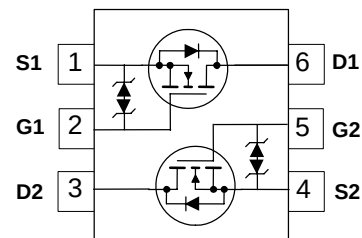
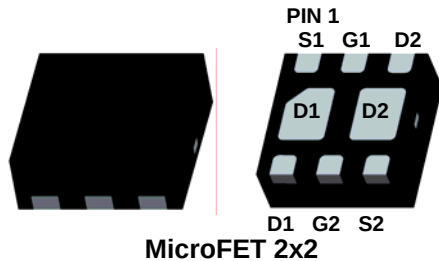
Dual N-Channel PowerTrench® MOSFET

General Description

This device is designed specifically as a single package solution for dual switching requirements in cellular handset and other ultra-portable applications. It features two independent N-Channel MOSFETs with low on-state resistance for minimum conduction losses. The MicroFET 2x2 offers exceptional thermal performance for its physical size and is well suited to linear mode applications.

Features

- 2.9 A, 30 V $R_{DS(ON)} = 123 \text{ m}\Omega$ @ $V_{GS} = 4.5 \text{ V}$
 $R_{DS(ON)} = 140 \text{ m}\Omega$ @ $V_{GS} = 3.0 \text{ V}$
 $R_{DS(ON)} = 163 \text{ m}\Omega$ @ $V_{GS} = 2.5 \text{ V}$
- Low profile – 0.8 mm maximum – in the new package MicroFET 2x2 mm
- RoHS Compliant



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 4.5\text{V}$)	2.9	A
	– Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 2.5\text{V}$)	2.7	
	– Pulsed	10	
P_D	Power Dissipation for Single Operation (Note 1a)	1.5	W
	Power Dissipation for Single Operation (Note 1b)	0.65	
T_J, T_{STG}	Operating and Storage Temperature	-55 to $+150$	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	83 (Single Operation)	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1b)	193 (Single Operation)	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1c)	68 (Dual Operation)	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1d)	145 (Dual Operation)	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
002	FDMA2002NZ	7"	8mm	3000 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		25		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			1	μA
I_{GSS}	Gate–Body Leakage Current	$V_{GS} = \pm 12\text{ V}, V_{DS} = 0\text{ V}$			± 10	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	0.4	1.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		–3		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = 4.5\text{ V}, I_D = 2.9\text{ A}$		75	123	m Ω
		$V_{GS} = 3.0\text{ V}, I_D = 2.7\text{ A}$		84	140	
		$V_{GS} = 2.5\text{ V}, I_D = 2.5\text{ A}$		92	163	
		$V_{GS} = 4.5\text{ V}, I_D = 2.9\text{ A}, T_C = 85^\circ\text{C}$		95	166	
		$V_{GS} = 3.0\text{ V}, I_D = 2.7\text{ A}, T_C = 150^\circ\text{C}$		138	203	
		$V_{GS} = 2.5\text{ V}, I_D = 2.5\text{ A}, T_C = 150^\circ\text{C}$		150	268	

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		190	220	pF
C_{oss}	Output Capacitance			30	40	pF
C_{rss}	Reverse Transfer Capacitance			20	30	pF

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 4.5\text{ V}, R_{GEN} = 6\text{ }\Omega$		6	12	ns
t_r	Turn–On Rise Time			8	16	ns
$t_{d(off)}$	Turn–Off Delay Time			12	21	ns
t_f	Turn–Off Fall Time			2	10	ns
Q_g	Total Gate Charge	$V_{DS} = 15\text{ V}, I_D = 2.9\text{ A},$ $V_{GS} = 4.5\text{ V}$		2.4	3.0	nC
Q_{gs}	Gate–Source Charge			0.35		nC
Q_{gd}	Gate–Drain Charge			0.75		nC

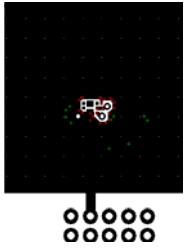
Drain–Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain–Source Diode Forward Current				2.9	A
V _{SD}	Drain–Source Diode Forward Voltage	I _S = 2.0 A		0.9	1.2	V
		I _S = 1.1 A		0.8	1.2	
t _{rr}	Diode Reverse Recovery Time	I _F = 2.9 A,		10		ns
Q _{rr}	Diode Reverse Recovery Charge	di _F /dt = 100 A/μs		2		nC

Electrical Characteristics

T_A = 25°C unless otherwise noted

- Notes:**
1. R_{θJA} is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design.
- (a) R_{θJA} = 83°C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB
 - (b) R_{θJA} = 193°C/W when mounted on a minimum pad of 2 oz copper
 - (c) R_{θJA} = 68°C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB
 - (d) R_{θJA} = 145°C/W when mounted on a minimum pad of 2 oz copper

	a) 83°C/W when mounted on a 1in ² pad of 2 oz copper		b) 193°C/W when mounted on a minimum pad of 2 oz copper
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- Scale 1 : 1 on letter size paper
2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

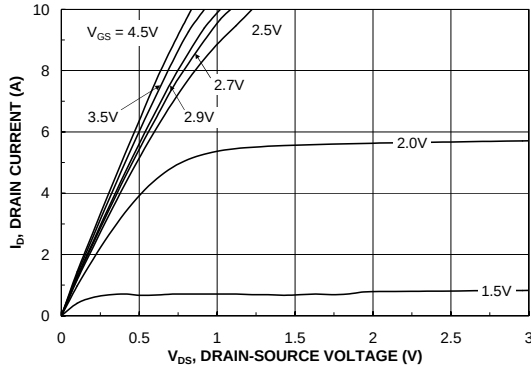


Figure 1. On-Region Characteristics.

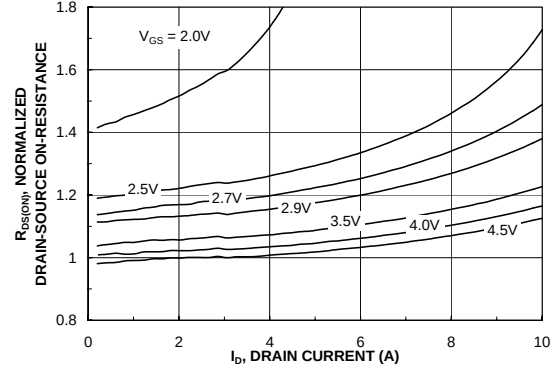


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

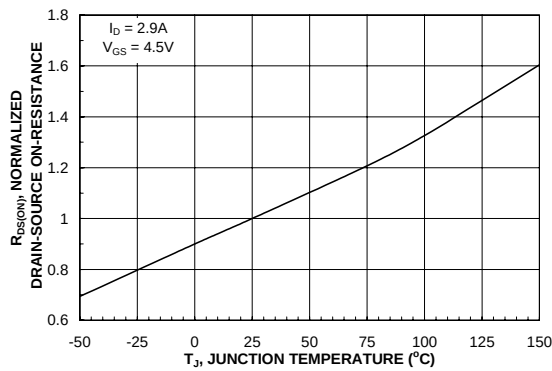


Figure 3. On-Resistance Variation with Temperature.

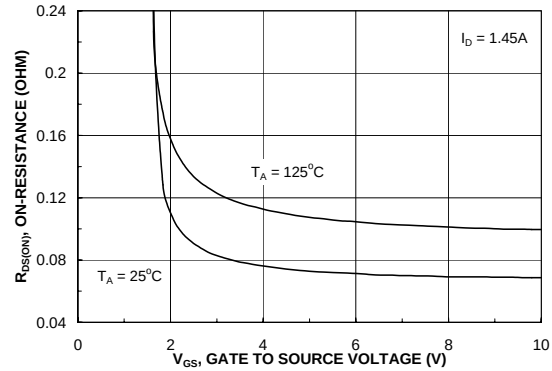


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

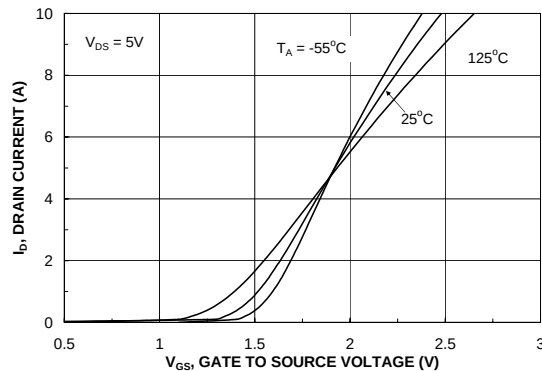


Figure 5. Transfer Characteristics.

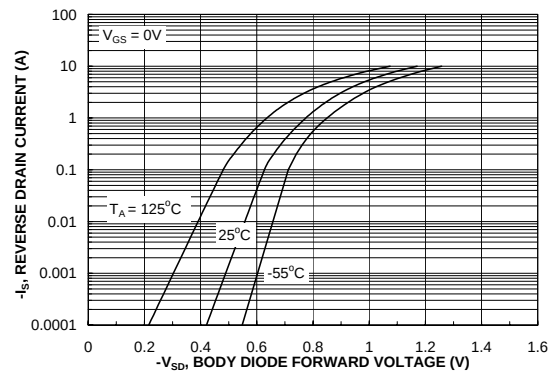


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

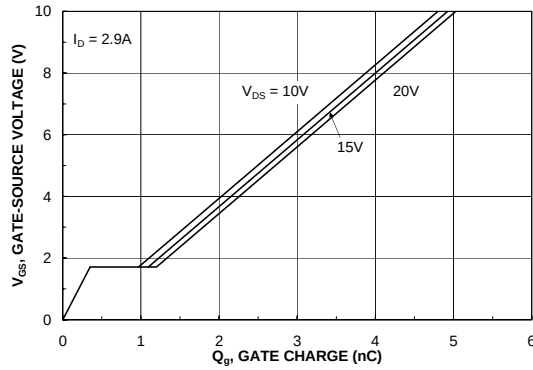


Figure 7. Gate Charge Characteristics.

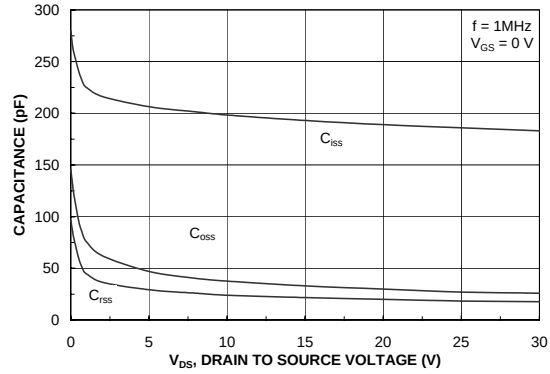


Figure 8. Capacitance Characteristics.

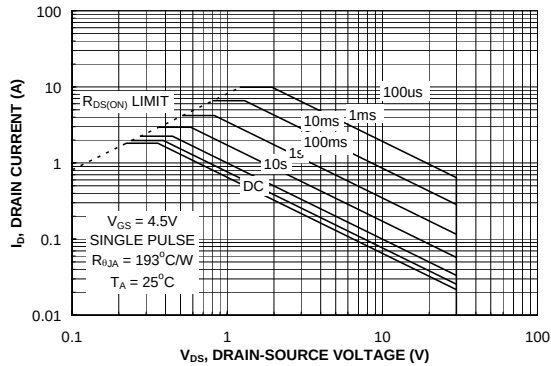


Figure 9. Maximum Safe Operating Area.

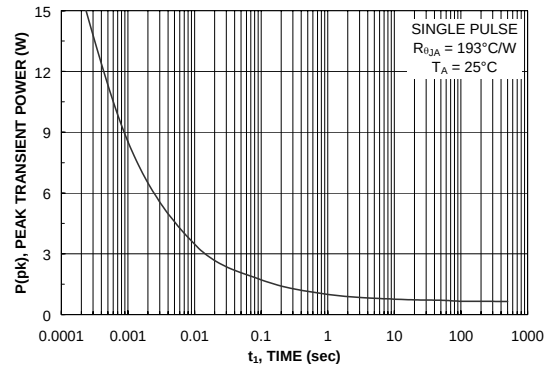


Figure 10. Single Pulse Maximum Power Dissipation.

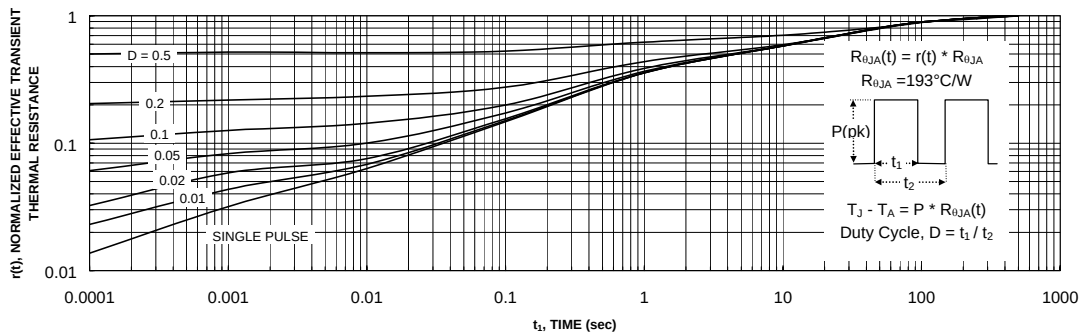
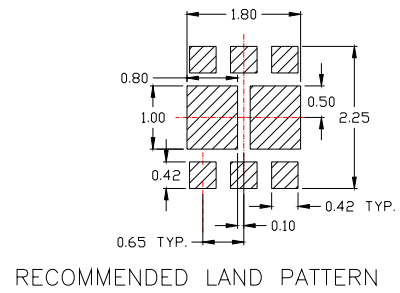
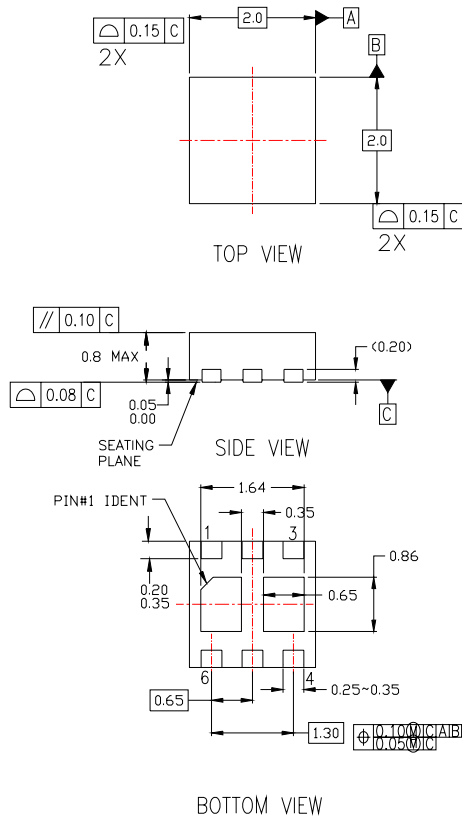


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VCCC, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

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